

Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 3723

Filed: September 28, 2000

Examiner: Not Yet Assigned

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE AND LAYER STRUCTURE MADE THEREBY

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith is a Preliminary Amendment for filing and the filing fee is calculated below:

For	No. After Amendment	Highest No. Prev. Filed	No. Extra	Rate	Fee
Total Claims	38	-	22 = 16	x \$ 9/\$18 = \$144	
Indep. Claims	3	-	3 = 2	x \$40/\$80 = \$	
TOTAL:					\$144

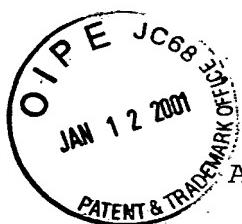
xx A check in the amount of \$144.00 is enclosed.

xx The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 05-1323 (Docket #2022/48819). A duplicate copy of this sheet is attached.

Respectfully submitted,

Richard R. Diefendorf
Registration No. 32,390

EVENSON, McKEOWN, EDWARDS
& LENAHAN, P.L.L.C.
1200 G Street, N.W., Suite 700
Washington, DC 20005
Telephone No.: (202) 628-8800
Facsimile No.: (202) 628-8844
RRD:msy



Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#3 Pre Amend A
L. Nelson
1/23/01

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 3723

Filed: September 28, 2000

Examiner: Not Yet Assigned

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE AND LAYER STRUCTURE MADE THEREBY

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please add the following new claims prior to examination:

A/ --23. A process of making a layer structure usable in manufacturing an integrated circuit comprising:

producing, in a single apparatus, a structure having deposits of conductive material in features defined in a patterned substrate which are physically isolated from each other by providing said patterned substrate, supplying an electrolyte solution out of which said conductive material can be plated, under an applied potential, over a surface of said patterned substrate, applying a potential so as to deposit a film of said conductive material out of the electrolyte solution and over said surface of said patterned substrate and polishing the film of said conductive material, and removing said conductive material from field regions of said patterned substrate while leaving said deposits of said conductive material in said features defined in said patterned substrate; and